



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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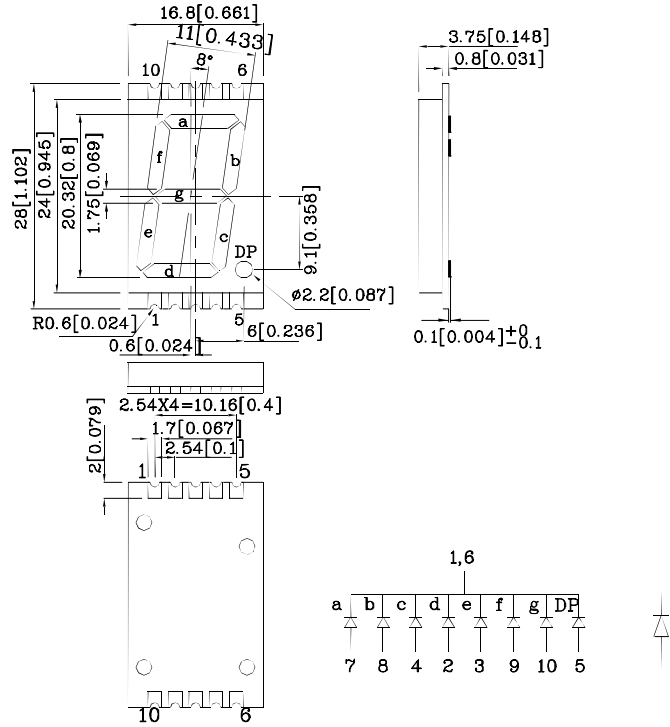
**Features**

- 0.8 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 200pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

**Package Schematics**



**Notes:**

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

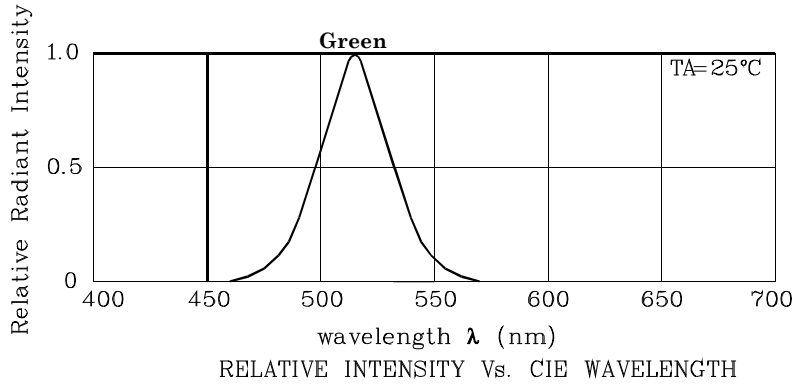
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		Green (InGaN)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	150	mA
Power Dissipation	P <sub>D</sub>	102.5	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		450	V

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

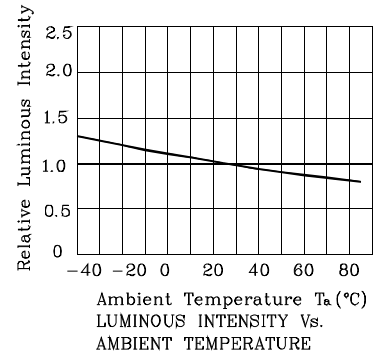
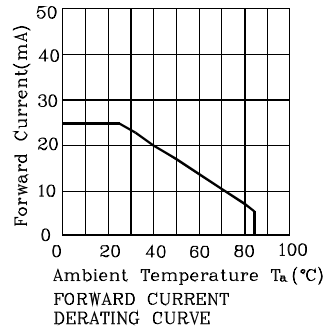
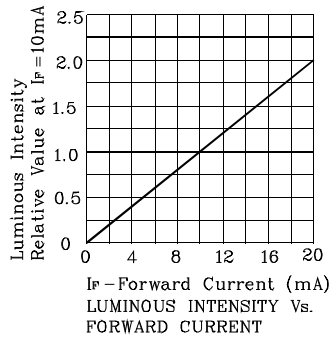
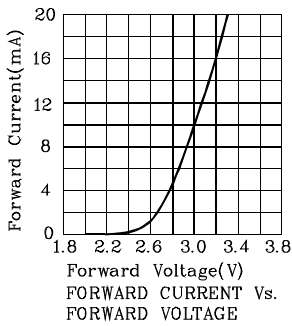
Operating Characteristics (T <sub>A</sub> =25°C)		Green (InGaN)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	3	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	4.1	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>P</sub>	515*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>D</sub>	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	35	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	45	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I <sub>F</sub> =10mA) ucd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Description
			min.	typ.		
XZFDGK20C-A	Green	InGaN	52000 21000*	117990 39990*	515*	Common Cathode, Rt.Hand Decimal.

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



❖ Green



**LED is recommended for reflow soldering and soldering profile is shown below.**

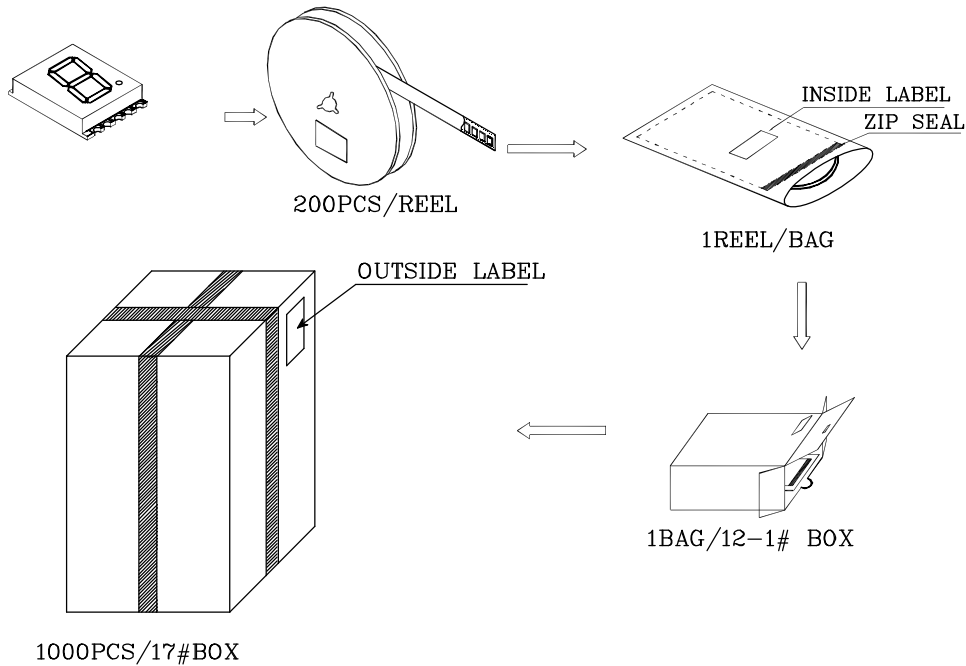
**Reflow Soldering Profile for SMD Products (Pb-Free Components)**



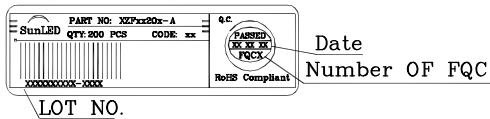
- Notes:
1. Maximum soldering temperature should not exceed 260°C
  2. Recommended reflow temperature: 145°C-260°C
  3. Do not put stress to the epoxy resin during high temperatures conditions



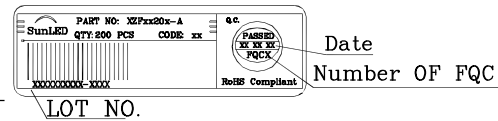
PACKING & LABEL SPECIFICATIONS



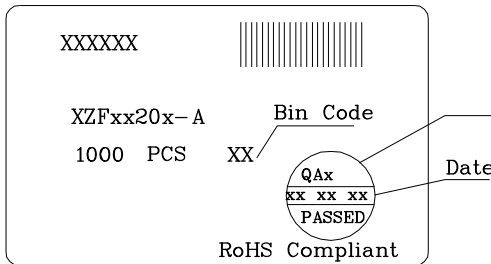
Inside Label On TAPE



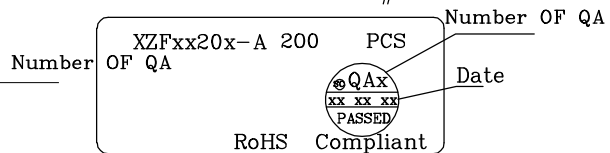
Outside Label On BAG



Outside Label On 19#Box



Outside Label On 12#Box



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1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
2. Contents within this document are subject to improvement and enhancement changes without notice.
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4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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6. Additional technical notes are available at <http://www.SunLEDusa.com/TechnicalNotes.asp>